

Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from, Europe, America and south Asia, supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts, Customers Priority, Honest Operation, and Considerate Service", our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip, ALPS, ROHM, Xilinx, Pulse, ON, Everlight and Freescale. Main products comprise IC, Modules, Potentiometer, IC Socket, Relay, Connector. Our parts cover such applications as commercial, industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



Contact us

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Email & Skype: info@chipsmall.com Web: www.chipsmall.com

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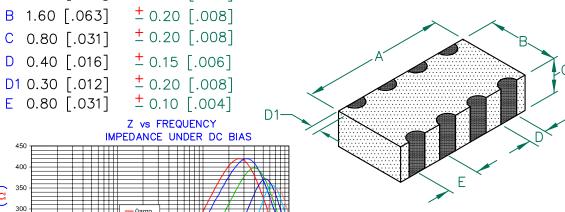


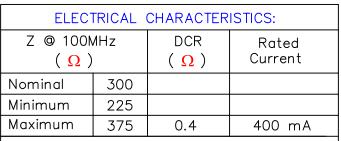




DA1206D301R-10

UNCONTROLLED DOCUMENT





LINE TO LINE INSULATION RESISTANCE >10M Ω AT 12 VOLTS.

.

NOTES: UNLESS OTHERWISE SPECIFIED

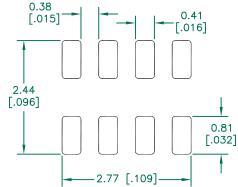
- 1. TAPED AND REELED per CURRENT EIA SPECIFICATIONS 7" REELS, 3000 PCS/REEL.
- 2. TERMINATION FINISH IS 100% TIN.
- 3. COMPONENTS SHOULD BE ADEQUATELY PREHEATED BEFORE SOLDERING.
- 4. OPERATING TEMPERATURE TEMP: -40°C~+125°C (INCLUDING SELF-HEATING)

± 0.20 [.008]

PHYSICAL DIMENSIONS:

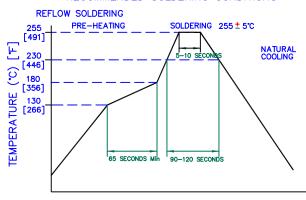
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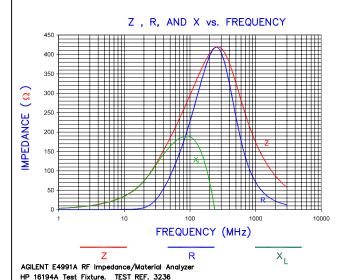
LAND PATTERNS FOR REFLOW SOLDERING



(For wave soldering, add 0.762 (0.030) to this dimension)

RECOMMENDED SOLDERING CONDITIONS







DIMENSIONS ARE IN mm [INCHES].				This print is the property of Laird			
				Tech, and is loaned in confidence subject to return upon request an	.d	■	T.
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				copies shall be made without the		.WII (
E	OPERATING TEMPERATURE UPDATE LAIRD LOGO	08/05/13	QU	written consent of Laird Tech. All rights to design or invention are reserved.	-		
D	UPDATE INSULATION RESISTANCE AND REFLOW	05/06/13	Qυ	PROJECT/PART NUMBER:	REV	PART TYPE:	DRAWN BY:
С	UPDATE COMPANY LOGO	05/21/09	עםו		I -		
		103/21/03	UKK	L D & 1 206D 301R = 10	1 -	CO_EIPE	I TMR
R	D1 chgd from 0.008 ±0.004 to 0.012 ±0.008.			DA1206D301R-10	E	CO-FIRE	TMB
В	D1 chgd from 0.008 ±0.004 to 0.012 ±0.008. ADD ROHS, UPDATE COMPANY LOGO	10/31/07	JRK	DATE: 03/30/04 SC	ALE: N		TMB
В			JRK	DATE: 03/30/04 SC	CALE: N	TS SHEET:	of 2